IECQ-CECC QC 88000-C001

COMPONENT ISSUE 2

SPECIFICATION March 2007

# Component Specification For Ceramic Hermetically Sealed Transistor Optocouplers



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#### **IEC**

International Electrotechnical Commission Commission Electrotechnique Internationale

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#### **FOREWORD**

The IECQ Quality Assessment System for Electronic Components (IECQ) is composed of those member countries of the International Electrotechnical Commission (IEC) who wish to take part in a harmonized system for electronic components of assessed quality. IECQ is also known in some European member countries as IECQ-CECC.

The object of the System is to facilitate international trade by the harmonization of the specifications and quality assessment procedures for electronic components, and by the grant of an internationally recognised Mark, or Certificate of Conformity. The components produced or services provided under the system are thereby acceptable in all member countries without further testing.

This Component Specification is based upon the requirements of IEC Publication QC 001002-2, and has been prepared by:

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#### **AMENDMENT RECORD**

No previous issue.

#### **REQUIREMENTS**

The requirements for IECQ-CECC Component Specifications as detailed in QC 001002-2 Amendment 1 clause 5.4 are satisfied by the following data sheet.

It should note that IECQ-CECC are not responsible for manufacturers declarations made in data sheets which fall outside the limits of approved detailed in IECQ-CECC certificates.

This Component Specification is intended for use with applicable IECQ-CECC Assessment Specifications. Eg: QC 88000-A0001



# **Ceramic Hermetically Sealed Transistor Optocouplers**

■ 4N24

**■ CSM165** 

■ CD500/501 ■ CSM200

■ CH300

■ CSM1200

■ CS200/201

■ CSM1224

**■ CS224** 

#### **Features**

- Release to IECQ-CECC
- Hermetically Sealed
- High Density Packaging
- 1500V DC withstand Test Voltage
- Low Input Requirements
- High Current Transfer Ratio

# **Applications**

- Military, high reliability system
- Medical instruments
- Mos, Cmos Applications
- Logic Interfacing
- Data Transmission
- Power Supply
- Modems

## **Description**

These devices are single, dual and quad, hermetically sealed optocouplers. Each channel is composed of a Gallium Arsenide infra-red emitting diode and a silicon phototransistor. Package styles for these devices include 6 pin, 8 pin, 16 pin flat pack, and hybrid 4 pin, with surface mount, butt cut and gull wing options available.

The same electrical die, assembly processes and materials are used for each channel of each device shown below. Therefore absolute maximum ratings, recommended operating conditions, electrical specifications and performance characteristics are identical for all units. Any exceptions, due to packaging variations and limitations, are as noted.



# **Selection Guide Package Styles and Configuration Options**

Package	6 pin DIP	6 pin DIP	6 pin LCC	8 pin DIP	16 pin Flat Pack	6 pin Metal Can TO-5
Lead Style						
Channels	1	1	2	2	4	1
Common Channel Wiring						

**Isocom Part Numbers and Options** 

	CS200/201	CS224	CSM200	CD500	CSM165	4N24
Commercial		CS200	CSM1200/1244	CD501		
	CM200/201/L2	CS224	CSM200/L2	CD500/L2		4N24/L2
Defense Screen Level		CS200/L2	CSM1200/1244/L2	CD501/L2	CSM165/L2	
	CS200/201/L2S	CS224	CSM200/L2S	CD500/L2S		4N24/L2S
Space Screen Level		CS200/L2S	CSM1200/1244/L2S	CD501/L2S	CSM165/L2S	
Standard Gold Plate Finish	Gold Plate	Gold Plate	Gold Plate	Gold Plate	Gold Plate	Gold Plate
Solder Dipped	Option 20	Option 20	Option 20	Option 20		
Butt Cut/Gold Plate	Option 10	Option 10	Option 10	Option 10		
Gull Wing/Solered	Option 30	Option 30	Option 30	Option 30		
Crew Cut/Gold Plate	Option 60	Option 60	Option 60	Option 60		

# **Functional Diagrams**

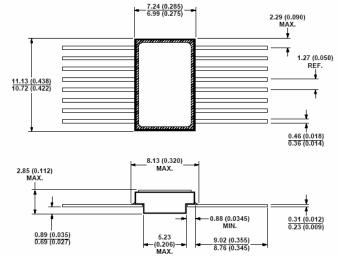
CH300 CSM200	CS200/201 CSM1200	CS224 CSM1224	CD500 CD501	CSM165/2/4
	6 pin DIP	6 pin DIP	8 pin DIP	16 pin Flat Pack
1 Channel	1 Channel	1 Channel	2 Channel	2*/4 Channel
4 3 52 12h 1 2	6 5 4   \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_	6 5 4 	8 7 6 5	16 15 14 13 12 11 10 9
4N24				
6 pin TO-5				
1 Channel				
5 2 2 1				

Note 2 channel is only for circuit of 2 middle channels 2 & 3 channel on the circuits.

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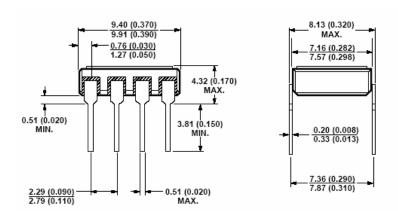
# **Outline Drawings**

#### 16 pin Flat Pack, 4 Channel



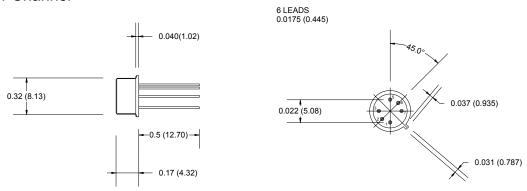
NOTE: DIMENSIONS IN MILLIMETERS

#### 8 pin DIP 2 Channel



#### NOTE: DIMENSIONS IN MILLIMETERS

#### 6 pin TO-5, 1 Channel



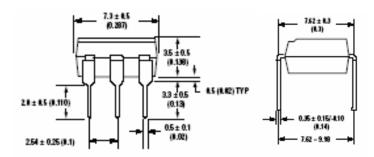
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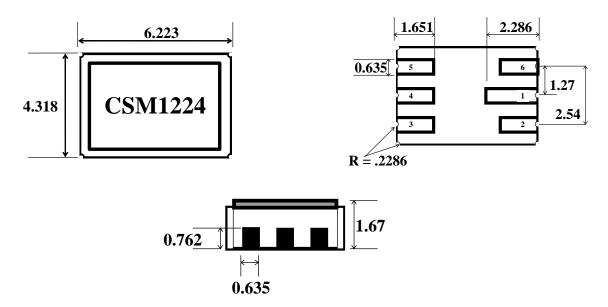
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#### 6 pin DIP 1 channel

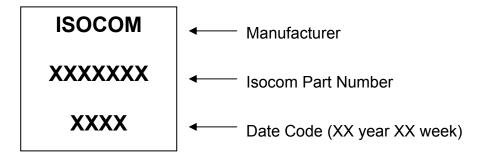


NOTE: DIMENSIONS IN MILLIMETERS

#### 6 Terminal LCC Surface Mount, 1 Channel



# **Device Marking**



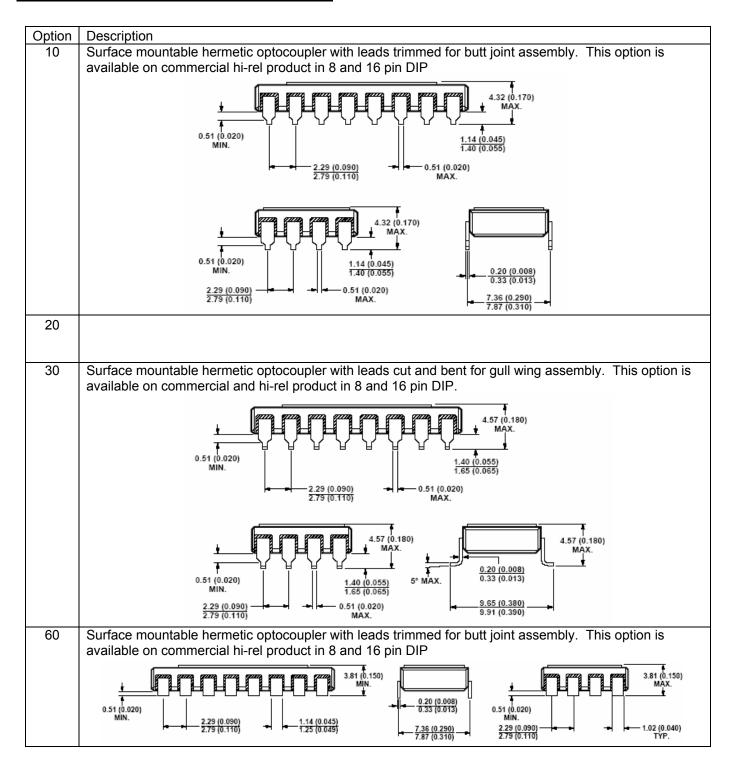
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## **Hermetic Optocoupler Options**





# **Absolute Maximum Ratings**

Storage Temperature	-65°C to +150°C
Operating Temperature	-55°C to +125°C
Lead Soldering Temperature	260°C 1.6mm from case for 10S
Input-to-Output Isolation Voltage	û1500VDC
	û500VDC for CH300

**Input Diode** 

Forward DC Current	50mA	
	15mA	For CH300
Reverse DC Voltage	7V	
	5V	For CH300
	3V	For CSM165
	2V	For CS224
Peak forward Current	1.5mA	≤ 10µS duration
Power Dissipation	100mW	Derate linearly above 100°C at 1.6W/°C.
	150mW	For CD500/501 andCSM165. Derate linearly above
		100°C at 1.4W/°C for CD500/501, and at 1.6 W/°C for CSM165
	25mW	For CH300

**Output Transistor** 

Collector-Emitter Voltage	50V	BV <sub>CEO</sub>
	30V	For CH300
	35V	For CS224
Emitter-Collector Voltage	7V	BV <sub>ECO</sub>
Collector-Base Voltage	70V	BV <sub>CBO</sub> For CS200/201 and CS224
	35V	For CS224
Collector Current	50mA	
	20mA	For CH300
Collector Current	100mA	t = 1mS
Power Dissipation	100mW	For CH300. Derate linearly above 100°C at 1.4W/°C
	150mW	For CS200/201, CS224, CD500/501 and CSM165.
		Derate linearly above 100°C at 1.4W/°C



Electrical Characteristics  $T_A = 25^{\circ}C$  U.O.S. (each channel where appropriate).

**Input Diode Electrical Characteristics** 

Parameter	Symbol	Test Conditions	Device	Min	Type	Max	Units
Forward Voltage	$V_{F}$	I <sub>F</sub> = 10mA		0.7	1.18	1.6	V
		$I_F = 10 \text{mA}, T_A = 125 ^{\circ}\text{C}$		0.7	1.10	1.6	
		$I_F = 10 \text{mA}, T_A = -55 ^{\circ}\text{C}$		0.7	1.29	1.6	
Reverse Breakdown	$V_R$	$I_R = 0.1 \text{mA}$		5	-	-	V
Voltage							
Reverse Current	$I_R$	$V_R = 3V$		-	-	100	μA
Capacitance	C <sub>IN</sub>	V = 0, f = 1MHz		-	25	-	pF

**Output Detector Electrical Characteristics** 

Collector-Emitter	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA		40	-	-	V
Breakdown Voltage			CH300	30			
(See note 1 below)							
Collector-Base Breakdown	$BV_CBO$	$I_B = 0.1 \text{mA}$		70	-	-	V
Voltage							
(See note 1 below)							
Emitter-Collector	$BV_{ECO}$	$I_{E} = 0.1 \text{mA}$		7	-	-	V
Breakdown Voltage							
Emitter-Base Breakdown	$BV_{EBO}$	$I_B = 0.1 \text{mA}$		5	-	-	V
Voltage							
Collector-Emitter Leakage	I <sub>CEO</sub>	$V_{CE} = 20V, I_{F} = 0$		-	6	100	μΑ
Current		$V_{CE} = 15v I_F = 0$	CSM165				
		$V_{CE} = 20V, I_F = 0, T_A = 125^{\circ}C$		-	8	100	μΑ

**Coupled Electrical Characteristics** 

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DC Current Transfer Ratio	IC/IF	$I_F = 10$ mA, $V_{CE} = 5$ V		50	-	-	%
			CS201	100			
(See note 3)		$I_F = 10 \text{mA}, V_{CE} = 5 \text{V}, T_A = 125 ^{\circ}\text{C}$	CS201	50	-	-	
		$I_F = 10 \text{mA}, V_{CE} = 5 \text{V}, T_A = -55 ^{\circ}\text{C}$	CS201	50	-	-	
		$I_F = 10 \text{mA}, V_{CE} = 5 \text{V}; T_A = -55 ^{\circ}\text{C} - 125 ^{\circ}\text{C}$		35	-	-	
Optical Crosstalk	I <sub>CEOX</sub>	$V_{CE} = 15v$ , , $I_F 2-4 = 10mA$ .	CSM165			250	μA
Collector-Emitter Saturation Voltage	V <sub>CE</sub> (Sat)	$I_F = 10 \text{mA}, I_C = 2.5 \text{mA}$		-	-	0.3	٧
		$I_F = 10 \text{mA}, I_C = 10 \text{A}$	CSM165			0.9	
		$I_F = 2mA, I_C = 0.2mA$	CH300			0.25	
Input to Output Capacitance	C <sub>IO</sub>	V <sub>IO</sub> = 0, f = 1mhz (See note 2 below)		-	3	5	pF
Input to Output Resistance	R <sub>IO</sub>	V <sub>IO</sub> = 500V (See note 2 below)		-	10 <sup>11</sup>	-	Ω
Isolation Voltage	V <sub>IO</sub>	(See note 2 below)	CH300	1500 500	-	-	VDC
Delay Time	td	$V_{CC}$ = 5V, $I_C$ = 2mA		-	4.0		μS
Rise Time	tr	R <sub>L</sub> = 100Ohms		-	5.0		μS
Storage Time	ts			-	0.7		μS
Fall Time	tf			-	5.0		μS
Turn -on Time	ton	$V_{CC} = 5V$ , $I_f = 5mA$		-	9		μS
Turn-off Time	t <sub>off</sub>	R <sub>L</sub> = 1KOhms		-	25		μS

- 1. BV<sub>CEO</sub> and BV<sub>CBO</sub> can be selected to suit customer specifications.
- 2. Measured between input when leads 1, 2 and 3 are shorted together and output when leads 4, 5 and 6 are shorted together.
- 3. A higher CTR can be selected to suit customer specification as a standard part.



# **Electrical Characteristics**

